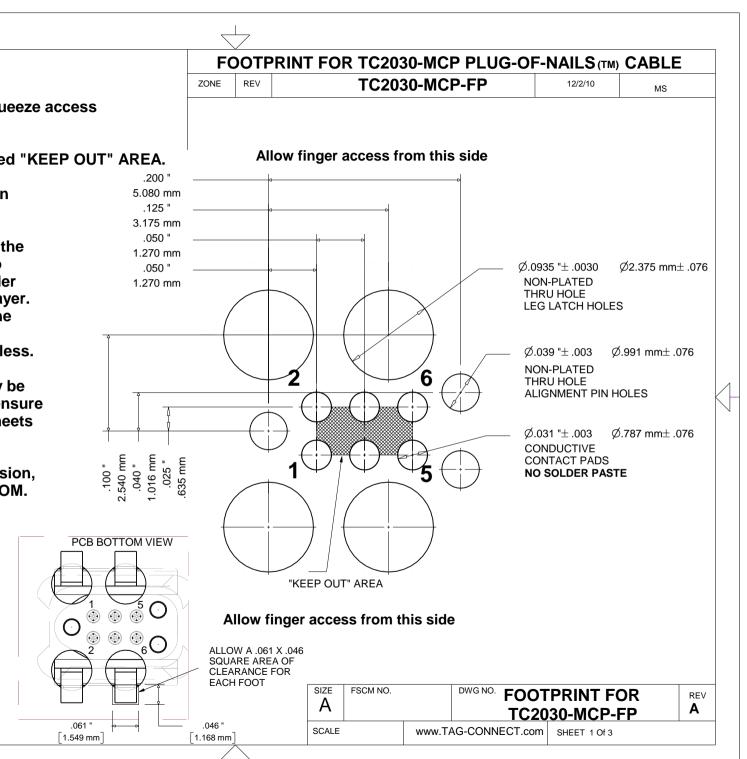
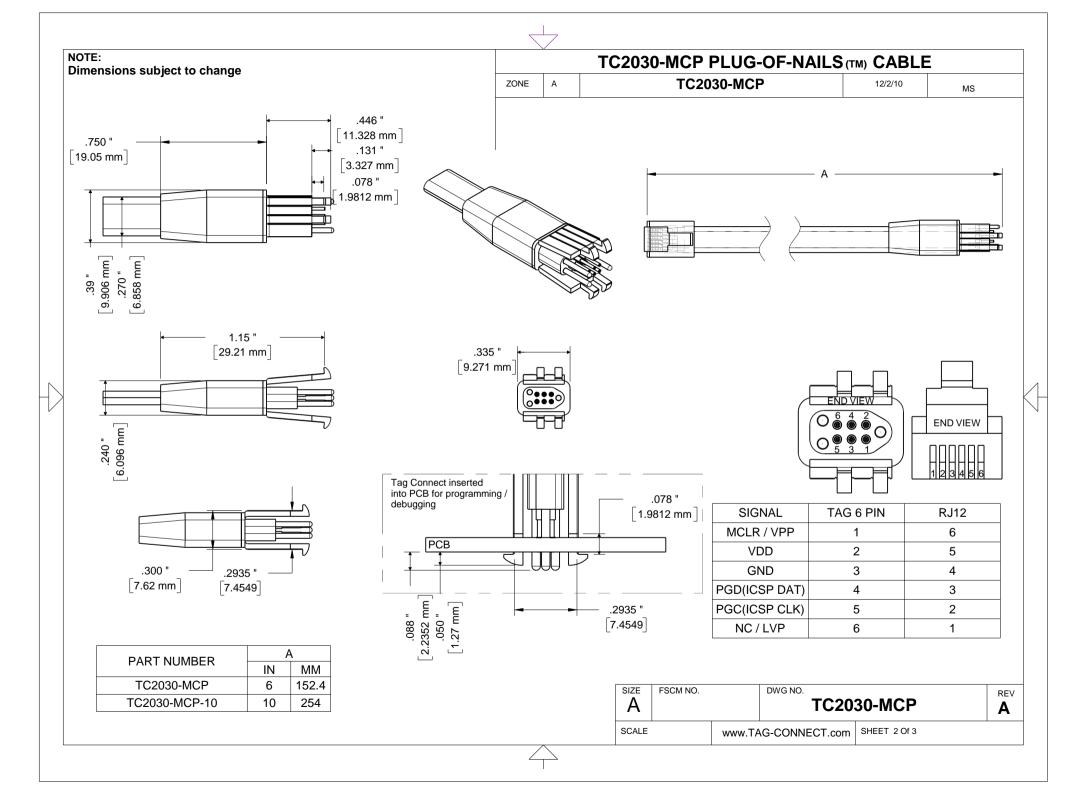
Notes:

- 1. Allow clearance for finger squeeze access from the two sides shown.
- 2. No tracks or vias in the shaded "KEEP OUT" AREA.
- 3. No other track or signal within .02" of any contact pad.
- 4. Do not allow solder paste on the contact pads It is essential to eliminate any hole in the solder paste-mask (solder stencil) layer. If this is not possible make the contact pads thru-hole with a finished hole size of .008" or less.
- 5. Leg and alignment holes may be plated and used as vias but ensure minimum finshed hole size meets specified tolerances.
- 6. To prevent purchasing confusion, please specify DNL in your BOM.

Microchip ICD / ICSP signals Pin 1: MCLR / Vpp Pin 2: Vdd Pin 3: GND Pin 4: PGD (ICSPDAT) Pin 5: PGC (ICSPCLK) Pin 6: Unused / LVP





Layout Problems to Avoid

